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CMLW6020S Series

Wire Wound SMD Power Inductor

◆ Features

1、Magnetic-resin shielded construction reduces buzz noise to ultra-low levels;
2、Metallization on ferrite core results in excellent shock resistance and damage-free durability;
3、Closed magnetic circuit design reduces leakage flux and Electro Magnetic Interference (EMI);
4、30% higher current rating than conventional inductors of equal size;
5、Take up less PCB real estate and save more power。

◆ Applications

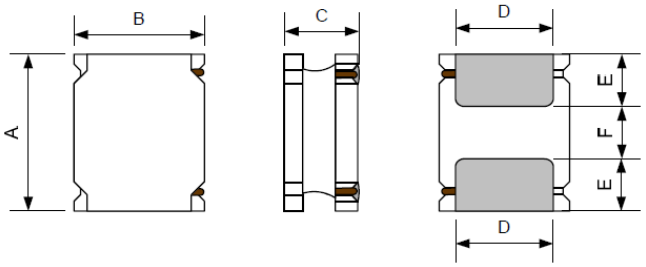
1、LED Lighting;
2、Mobile devices with multifunction such as adding color TV and camera;
3、Flat-screen TVs, blue-ray disc recorders, set top boxes;
4、Notebooks, desktop computers, servers, graphic cards;
5、Portable gaming devices, personal navigation systems, personal multimedia devices;
6、Automotive systems
7、Telecomm base stations

◆ Lead Free Part Numbering

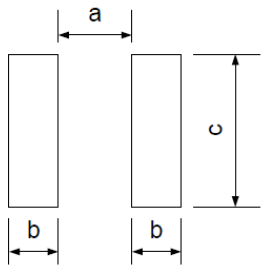
CMLW	6020	S	100	M	S	T
(1)	(2)	(3)	(4)	(5)	(6)	(7)

(1) Series Type
(2) Dimension：L X H
(3) Material Code
(4) Inductance：2R2=2.2μH；
100=10μH；101=100μH
(5) Inductance Tolerance：M=±20%, N=±30%
(6) Company Code
(7) Packaging：Tape Carrier Package

◆ Dimensions



Recommended Land Pattern



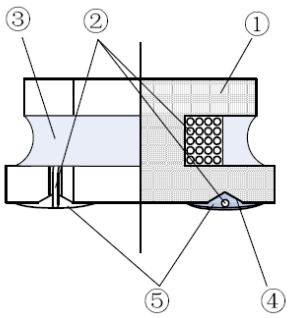
Unit:mm

Series	A	B	C	D	E	F	a Typ.	b Typ.	c Typ.
CMLW6020S	6.0±0.3	6.0±0.3	2.0Max.	4.9±0.3	1.55±0.3	2.90±0.3	2.8	1.7	5.7

◆ Electrical Characteristics

1) Operating and storage temperature range (individual chip without packing): cking): -25℃ ~ +125℃
2) Storage temperature range (packaging conditions): -10℃~+40℃ and RH 70% (Max.)

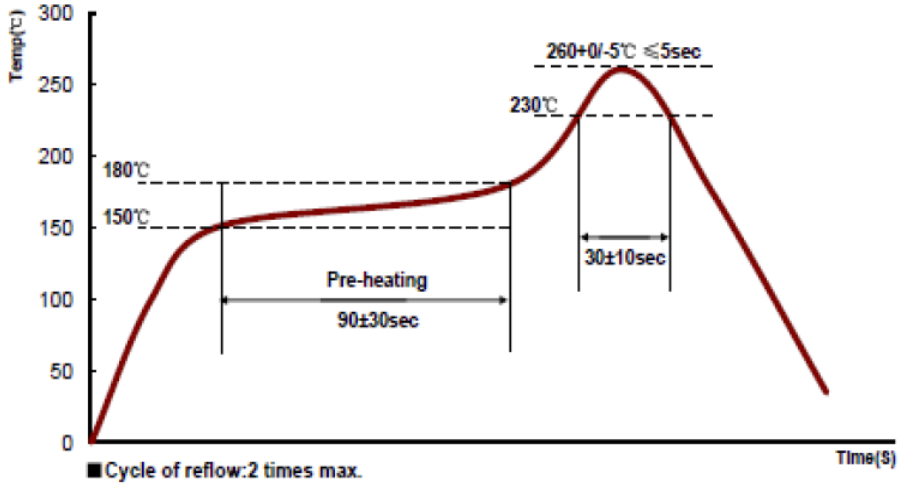
◆ Construction and material



Code	Part Name	Material Name
①	Ferrite Core	Ni-Zn Ferrite
②	Wire	Polyurethane system enameled copper wire
③	Magnteic Glue	Epoxy resin and magnetic powder
④	Plating Electrodes	Ag
		Ni
		Sn
⑤	Outer Electrodes	Top surface solder coating Sn 、Ag、Cu

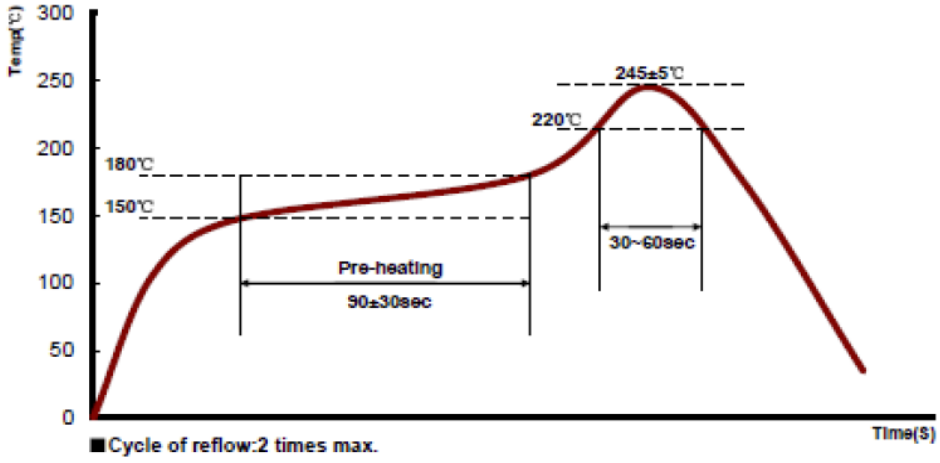
◆ REFLOW-PROFILE

Limit Profile



■Cycle of reflow:2 times max.

Standard Profile (for EOC Solder paste S70G-HF)



■Cycle of reflow:2 times max.

◆ Specification

Part Number	Inductance @100KHz,1V (μH)	DC Resistance ±30% (Ω) DCR	Min.Self-resonant Frequency（MHz） S.R.F	Saturation Current(A) Isat	Heat Rating Current (A) Irms
CMLW6020S Series					
CMLW6020SR68NST	0.68±30%	0.017	120	7.50	3.80
CMLW6020S1R0MST	1.0±20%	0.020	94	4.15	3.25
CMLW6020S1R5MST	1.5±20%	0.022	79	4.25	3.20
CMLW6020S2R2MST	2.2±20%	0.028	61	3.75	2.75
CMLW6020S3R3MST	3.3±20%	0.035	51	3.15	2.60
CMLW6020S4R7MST	4.7±20%	0.058	41	3.00	2.00
CMLW6020S5R6MST	5.6±20%	0.058	36	2.40	1.90
CMLW6020S6R8MST	6.8±20%	0.079	31	2.20	1.80
CMLW6020S8R2NST	8.2±20%	0.105	28	2.10	1.40
CMLW6020S100MST	10±20%	0.105	27	1.75	1.40
CMLW6020S150MST	15±20%	0.145	21	1.50	1.20
CMLW6020S220MST	22±20%	0.204	16	1.25	1.00
CMLW6020S330MST	33±20%	0.300	11	0.96	0.85
CMLW6020S470MST	47±20%	0.410	10	0.70	0.80

◆ Note

1：All test data is referenced to 20°C ambient;

2：Rated current: Isat or Irms, whichever is smaller;

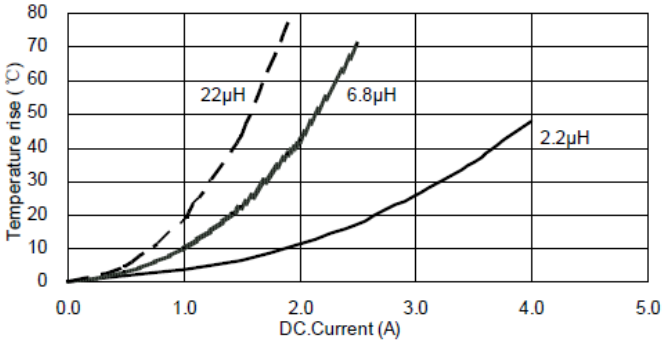
3：Isat: DC current at which the inductance drops approximate 30% from its value without current;

4：Irms: DC current that causes the temperature rise (△T =40°C) from 20°C ambient.

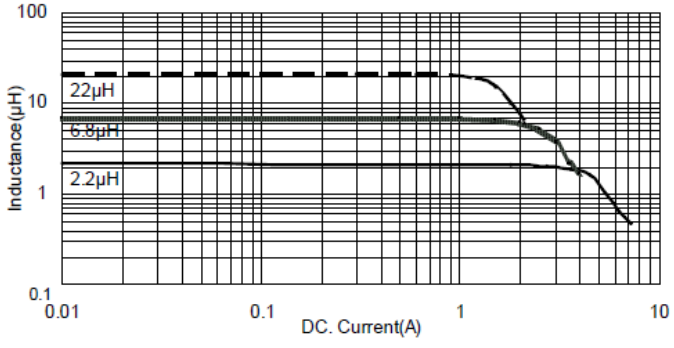
◆ TYPICAL ELECTRICAL CHARACTERISTICS

CMLW6020S Series

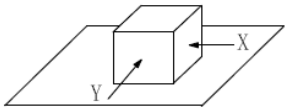
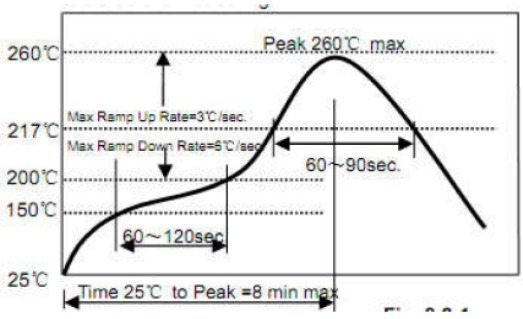
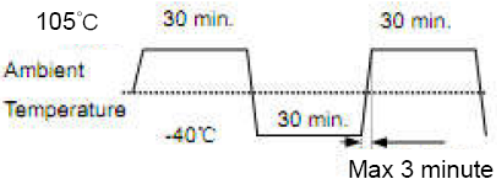
Temperature vs. DC Current Characteristics



Inductance vs. DC Current Characteristics

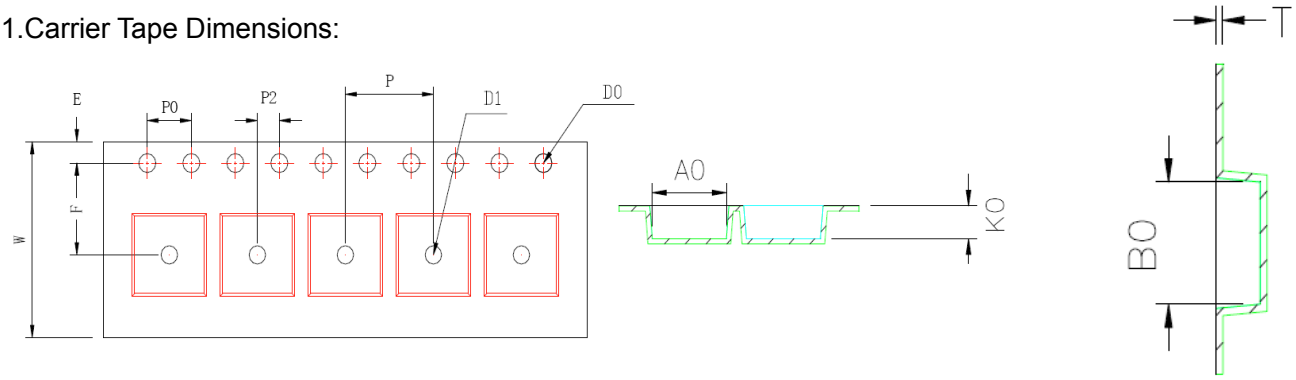


◆Reliability Test

Items	Requirements	Test Methods and Remarks
A. Terminal Strength	No removal or split of the termination or other defects shall occur.  Fig.7.1-1	1) Solder the inductor to the testing jig (glass epoxy board shown in Fing.7.1-1) using eutectic solder. Then apply a force in the direction of the arrow. 2) 10N force. 3) Keep time: 5±2s
B. High Temperature	1. No visible mechanical damage. 2. Inductance change: Within ±10%	1) Storage Temperature :125+/-5℃ 2) Duration : 96 ±4 Hours 3) Recovery : then measured at room ambient temperature after placing 24 hours.
C. Low Temperature	1. No visible mechanical damage 2. Inductance change: Within ±10%	1) Temperature and time: -40±5℃ 2) Duration: 96±4 hours 3) TRecovery : then measured at room ambient temperature after placing 24 hours.
D. Vibration test	1. No visible mechanical damage. 2. Inductance change: Within ±10%	1) Frequency range:10HZ~55HZ~10HZ 2) Amplitude:1.5mm p-p 3) Direction:X,Y,Z 4) Time:1 minute/cycle,2hours per axis
E. High Temperature Storage Tested	1. No visible mechanical damage. 2. Inductance change: Within ±10%	1) Storage Temperature :60+/-2℃ 2) Relative Humidity :90-95% RH 3) Duration : 96 ±4 Hours 4) Recovery : then measured at room ambient temperature after placing 24 hours.
F. Resistance to Soldering Heat	1. No visible mechanical damage. 2. Inductance change: Within ±10%  Fig. 1	1) Re-flowing Profile: Please refer to Fig. 1 2) Test board thickness: 1.0mm 3) Test board material: glass epoxy resin 4) The chip shall be stabilized at normal condition for 1~2 hours before measuring
G. Thermal Shock	1. No visible mechanical damage. 2. Inductance change: Within ±10%  Fig. 2	1) Temperature and time: -40±3℃ for 30±3 min→105℃ for 30±3min, please refer to Fig. 2. 2) Transforming interval: Max, 3 minute 3) Tested cycle: 100 cycles 4) The chip shall be stabilized at normal condition for 1~2 hours before measuring

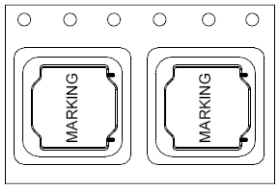
◆Packaging and Marking:

1.Carrier Tape Dimensions:

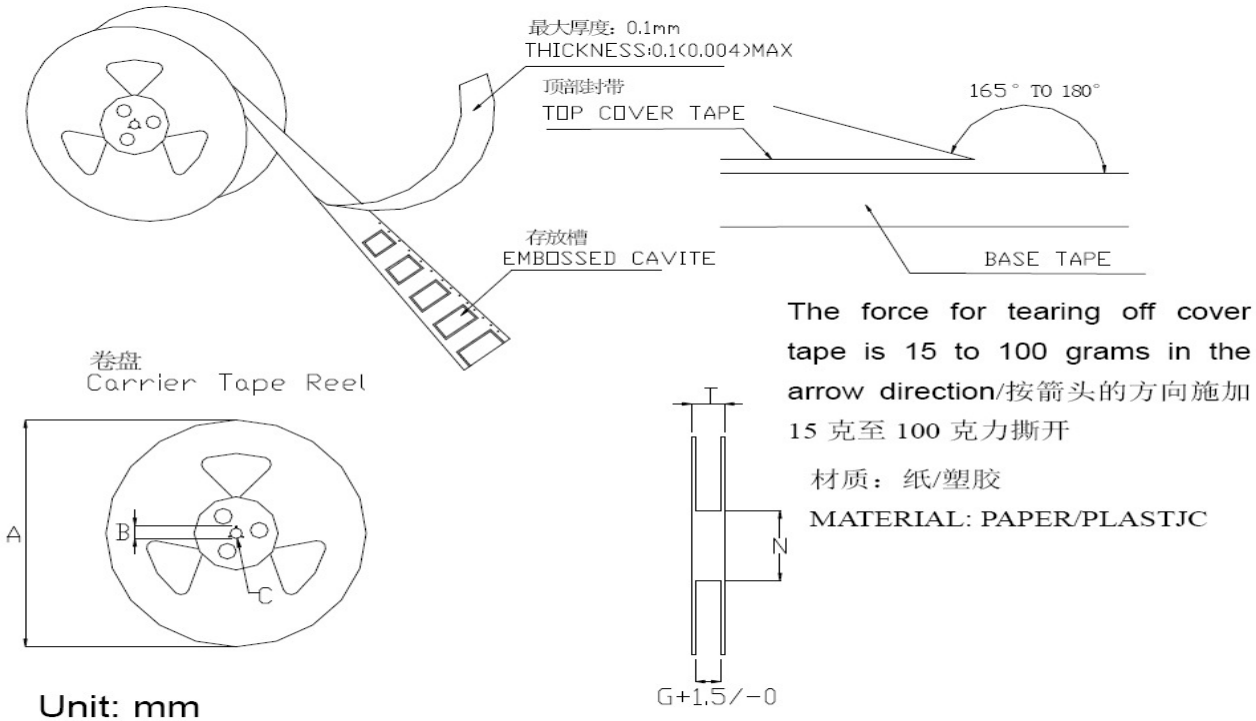


ITEM	W	A0	B1	K0	P	F	E	D0	D1	P0	P2	T
DIM	12.00	6.3	6.3	2.5	8.00	5.50	1.75	1.50	1.50	4.00	2.00	0.35
TOLE	±0.3	±0.1	±0.1	±0.1	±0.1	±0.15	±0.1	+0.1	+0.1	±0.1	±0.1	±0.05

2.Taping Dimensions:



3.Reel Dimensions:



Unit: mm

Type	A	B	C	G	N	T
12mm	330	21±0.8	13±0.4	12.4	100	16.4

4. Packaging Quantity:

Standard Packing Quantity：2500 pcs/reel Or 3000 pcs/reel